

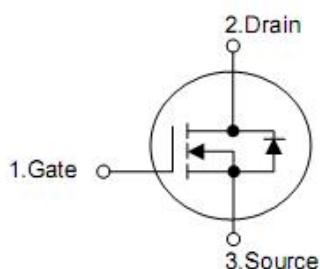
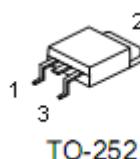
## 1. Features

- $R_{DS(ON)}=8.5\text{m}\Omega$ (Typ.),  $V_{GS}=10\text{V}$
- Advanced trench process technology
- High density cell design for ultra low on-resistance
- Fully characterized avalanche voltage and current

## 2. Applications

- DC-DC Switching
- MOTO Control
- Power Bank
- LED Lighting Power

## 3. Pin configuration



Pin	Function
1	Gate
2	Drain
3	Source

## 4. Maximum ratings and thermal characteristics

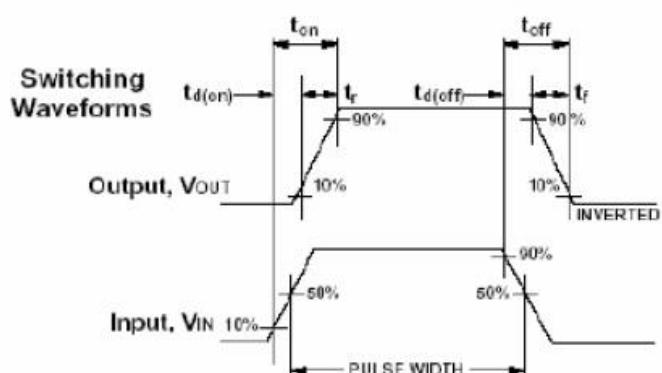
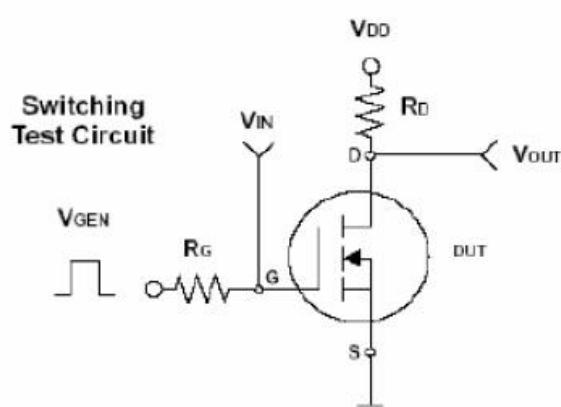
(Ta=25°C,unless otherwise notes)				
Rating	Symbol	Value	Unit	
Drain-source voltage	V <sub>DS</sub>	30	V	
Gate-source voltage	V <sub>GS</sub>	$\pm 20$	V	
Continuous drain current	I <sub>D</sub>	40	A	
Pulsed drain current <sup>4</sup>	I <sub>DM</sub>	160	A	
Maximum power dissipation	T <sub>A</sub> =25°C	P <sub>D</sub>	60	W
Operating junction and storage temperature range	T <sub>J</sub> /T <sub>STG</sub>	-55 to 150	°C	
Junction-to-case thermal resistance	R <sub>θJC</sub>	2	°C/W	
Junction-to ambient themal rasistance (PCB mount) <sup>2</sup>	R <sub>θJA</sub>	50	°C/W	

Note:  
 1.Repetitive rating:pulse width limited by the maximum junction temperation  
 2.1-in<sup>2</sup> 2oz Cu PCB board  
 3.Guaranteed by design;not subject to production testing  
 4.Notes:Pulse width $\leq$ 300μs,duty cycle $\leq$ 2%

## 5. Ordering information

Part number	Package
KND9103A	TO-252

## 6. Typical application circuit



## 7. Electrical characteristics

(Ta=25°C,unless otherwise notes)

Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Units
<b>Static</b>						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V,I <sub>D</sub> =250μA	30	-	-	V
Drain-source on-state resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V,I <sub>D</sub> =30A	-	8.5	10.5	mΩ
		V <sub>GS</sub> =4.5V,I <sub>D</sub> =20A	-	13.5	18	mΩ
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	1	1.6	3	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =24V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-source forward leakage	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
<b>Dynamic<sup>3</sup></b>						
Total gate charge	Q <sub>g</sub>	I <sub>D</sub> =30A V <sub>DS</sub> =15V V <sub>GS</sub> =10V	--	8	--	nC
Gate-source charge	Q <sub>gs</sub>		--	3	--	nC
Gate-drain (“miller”)charge	Q <sub>gd</sub>		--	2.8	--	nC
Turn-on delay time	t <sub>d(off)</sub>	V <sub>DD</sub> =15V I <sub>D</sub> =1A R <sub>G</sub> =6Ω R <sub>L</sub> =15Ω V <sub>GEN</sub> =10V	--	12	--	ns
Rise time	t <sub>r</sub>		--	5	--	ns
Turn-off delay time	t <sub>d(off)</sub>		--	28	--	ns
Fall time	t <sub>f</sub>		--	5	--	ns
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V V <sub>DS</sub> =15V f=1.0MHz	--	910	--	pF
Output capacitance	C <sub>oss</sub>		--	190	--	pF
Reverse transfer capacitance	C <sub>rss</sub>		--	95	--	pF
Source-drain body diode characteristics T <sub>J</sub> =25°C,unless otherwise notes						
Diode continuous forward current <sup>4</sup>	I <sub>s</sub>	T <sub>J</sub> =25°C		0.8	40	A
Diode forward voltage	V <sub>SD</sub>	I <sub>s</sub> =20A,V <sub>GS</sub> =0V		0.8	1.5	V

## 8. Typical characteristics

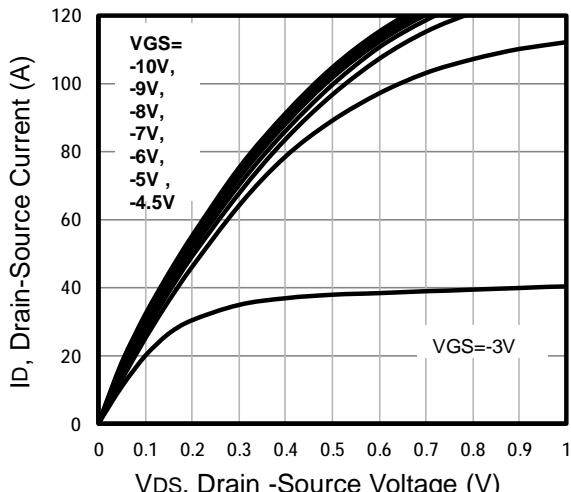


Fig1. Typical Output Characteristics

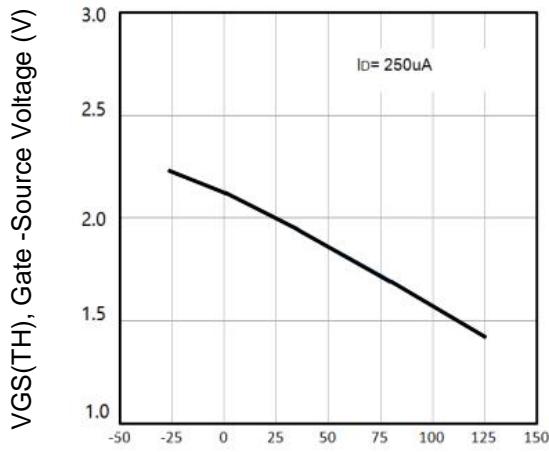


Fig2. Threshold Voltage Vs. Temperature  
 $T_c$ , Case Temperature (°C)

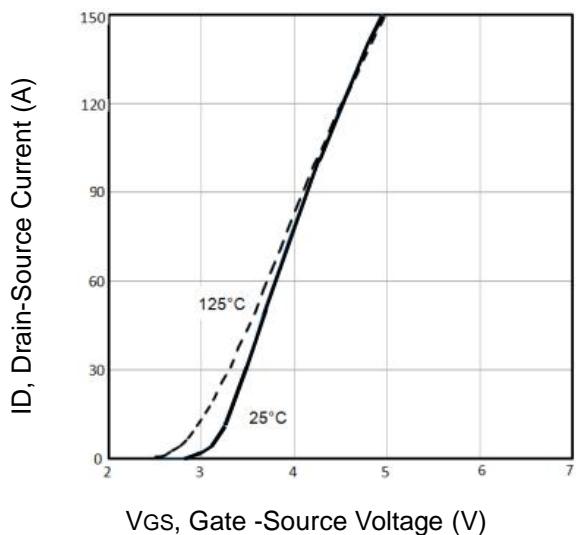


Fig3. Typical Transfer Characteristics

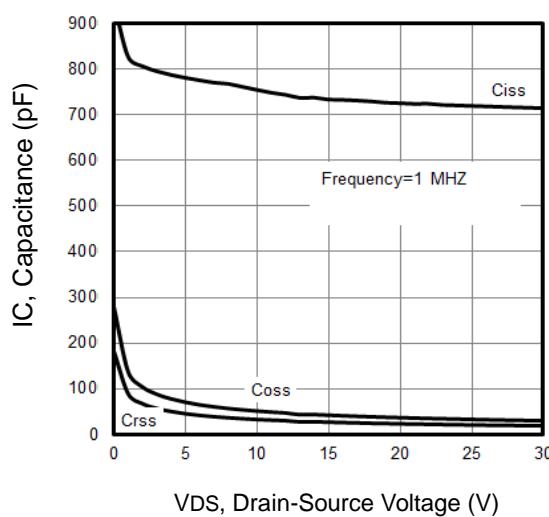


Fig4. Typical Capacitance Vs. Drain-Source Voltage

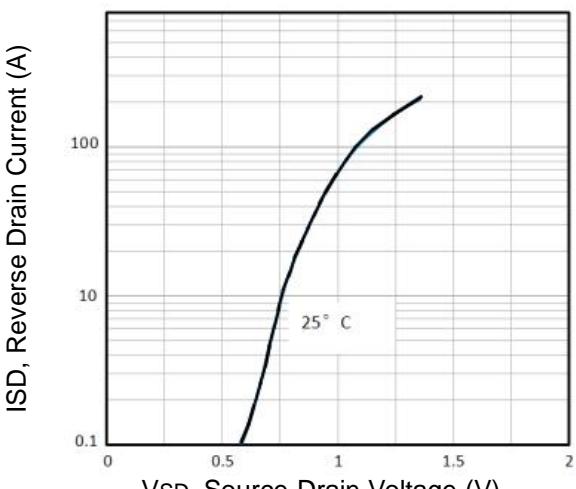


Fig5. Typical Source-Drain Diode Forward Voltage

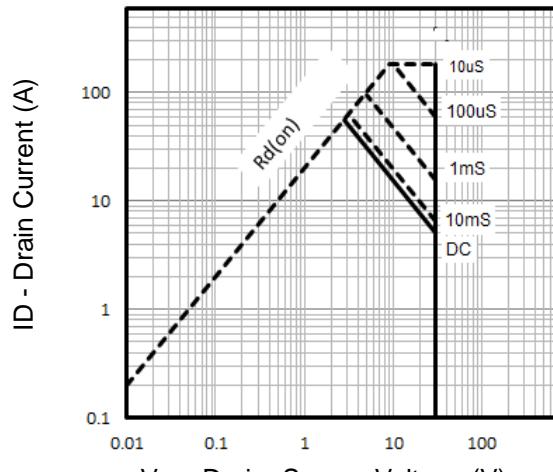


Fig6. Maximum Safe Operating Area